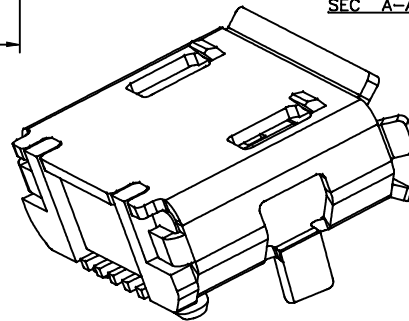
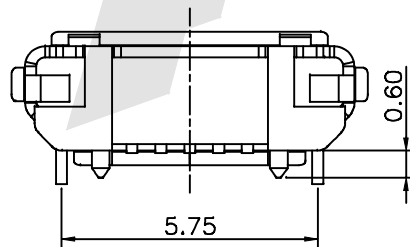
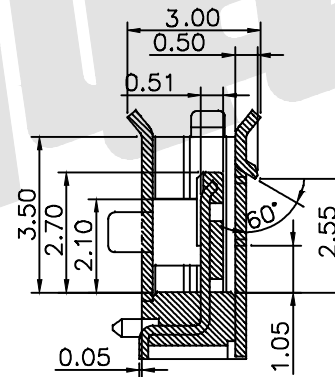
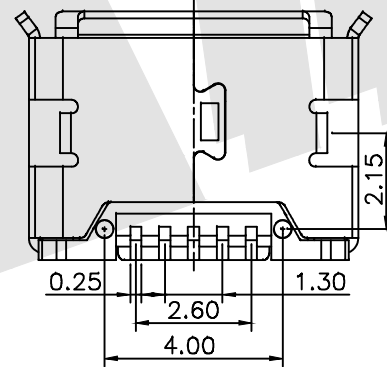
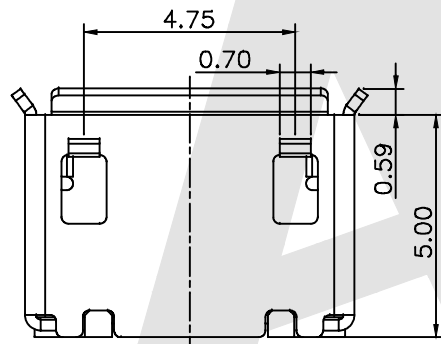
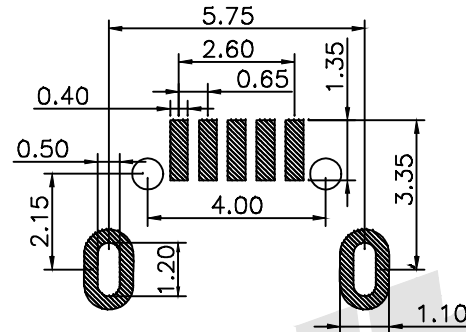
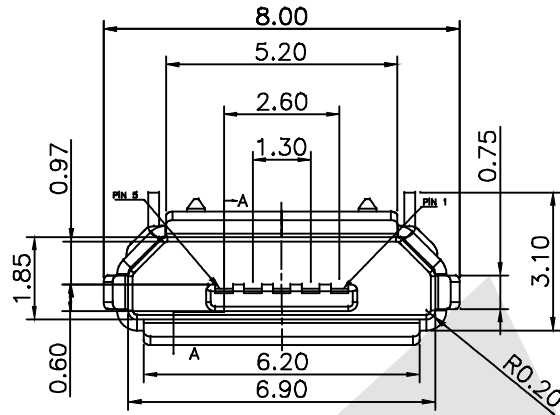


HSF



Notes:

1. Materials:

- 1.1 Housing: High temperature thermoplastic with g, f UL94V-0
- 1.2 Contact copper alloy t=0.15mm
- 1.3 Shell: copper alloy t=0.30mm

2. Specifications:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100v(ac) for 1min
- 2.3 Contact resistance: 50mV Max
- 2.4 Insulation resistance: 100MW Min
- 2.5 Total mating force: 3.57Kgf Max
- 2.6 Total unmating force: 1.0Kgf Min 0.81-2.05Kgf Min. after 10000 insertion extraction cycles
- 2.7 Temperature range: -30°C TO +80°C

Order code:

MUFM16 - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥

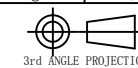
- ① Series NO:
- ② Shell Material:
B: Brass I: Iron
S: stainless steel
- ③ Insulator Material:
P: PBT+30%GF
L: LCP
- ④ Contact Material:
B: Brass
P: phosphor copper
- ⑤ Contact Plating:
G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
- ⑥ Packing:
A: Tray
B: Bag
C: Tube
D: Tape & Reel

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

Antenk® ANTENK ELECTRONICS CO., LTD
 Http://www.antenk.com
 E-mail: sales@antenk.com

SCALE: As Shown UNIT: mm
 DRAW Lv Xun Hua DATE 01/06/2019
 CHECK BobYang DATE 01/06/2019

TITLE: MICRO USB SMT 5P RECEPTACLE B TYPE,
 Shell dip with Post



DRAWING NO: MUFM16-XXXXX
 PRODUCT NO: MUFM16-XXXXX

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		